



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISZ0804NLS	Issued	23. June 2021
MA#	MA005431948		
Package	PG-TSDSON-8-26	Weight*	36.61 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.510	1.39	1.39	13917	13917
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		269	
	non noble metal	iron	7439-89-6	0.197	0.54		5373	
	non noble metal	copper	7440-50-8	7.988	21.82	22.40	218177	223886
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	759	759
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1013	
	plastics	epoxy resin	-	1.911	5.22		52192	
	inorganic material	silicondioxide	60676-86-0	16.605	45.35	50.67	453512	506717
leadfinish	non noble metal	tin	7440-31-5	0.395	1.08	1.08	10796	10796
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	555	555
solder	non noble metal	tin	7440-31-5	0.016	0.04		423	
	noble metal	silver	7440-22-4	0.019	0.05		529	
	non noble metal	lead	7439-92-1	0.740	2.02	2.11	20215	21167
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2766	
	non noble metal	copper	7440-50-8	4.112	11.23	11.52	112317	115256
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2567	
	non noble metal	copper	7440-50-8	3.816	10.42	10.69	104220	106947
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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